

ME45P03A-VB Datasheet

P-Channel 30-V (D-S) MOSFET

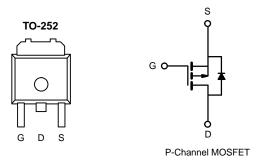
PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^d	Q _g (Typ.)		
- 30	0.018 at V _{GS} = - 10 V	- 40	13 nC		
- 30	0.025 at V _{GS} = - 4.5 V	- 35	13110		

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- Trench Power MOSFET
- 100 % Rg Tested

APPLICATIONS

- Load Switch
- Battery Switch



Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	- 30	V		
Gate-Source Voltage		V _{GS}	± 20	v	
	T _C = 25 °C		- 40		
Continuous Drain Current (T ₁ = 150 °C)	T _C = 70 °C		- 35		
Continuous Drain Current $(1) = 150^{\circ}$ C)	T _A = 25 °C	I _D	- 30.0 ^{a, b}		
	T _A = 70 °C		- 28 ^{a, b}	A	
Pulsed Drain Current	I _{DM}	- 150			
Continuous Source-Drain Diode Current	T _C = 25 °C	1-	- 3.5		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 2.1 ^{a, b}		
	T _C = 25 °C		40		
Maximum Davies Dissis ation	T _C = 70 °C		27		
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	W	
	T _A = 70 °C	1	1.6 ^{a, b}		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	40	50	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	24	30	C/VV	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 95 °C/W.

d. Based on $T_C = 25 \text{ °C}$.

FREE

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SPECIFICATIONS T _J = 25 °C			Min	There	Merr	Unit	
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		V 0.V/L 0500		1	1		
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	I _D = - 250 μA		- 31		mV/°C	
	$G_{S(th)}$ Temperature Coefficient $\Delta V_{GS(th)}/T_J$			4.5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.0		- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55 \text{ °C}$			- 1 - 5	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 V, V_{GS} = -10 V$	- 40		5	A	
Drain-Source On-State Resistance ^a	R _{DS(on)}			0.018		Ω	
Dialit-Source Off-State Resistance	VDS(on)	V_{GS} = - 4.5 V, I _D = - 5.6 A		0.025		52	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 7.0 A		18		S	
Dynamic ^b							
Input Capacitance	C _{iss}			1455			
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		180		pF	
Reverse Transfer Capacitance	C _{rss}			145			
Total Gate Charge	Q _q	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -7.0 \text{ A}$		25	38	-	
Total Gate Gharge	8	0		13	20		
Gate-Source Charge	Q _{gs}	V_{DS} = - 15 V, V_{GS} = - 4.5 V, I_{D} = - 7.0 A		3.5			
Gate-Drain Charge	Q _{gd}			5.5			
Gate Resistance	R _g	f = 1 MHz	0.4	2.0	4.0	Ω	
Turn-On Delay Time	t _{d(on)}			10	20		
Rise Time	t _r	V_{DD} = - 15 V, R_L = 2.7 Ω		13	20		
Turn-Off DelayTime	t _{d(off)}	$\rm I_D \cong$ - 5.6 A, $\rm V_{GEN}$ = - 10 V, $\rm R_g$ = 1 Ω		23	35		
Fall Time	t _f			9	18	ns	
Turn-On Delay Time	t _{d(on)}			38	57	115	
Rise Time	t _r	V_{DD} = - 15 V, R_L = 2.7 Ω		89	134		
Turn-Off DelayTime	t _{d(off)}	$I_{D}\cong$ - 5.6 A, V_{GEN} = - 4.5 V, R_{g} = 1 Ω		22	33		
Fall Time	t _f			11	17		
Drain-Source Body Diode Characteris	stics						
Continous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 6.5	A	
Pulse Diode Forward Current	I _{SM}				- 30	A	
Body Diode Voltage	V_{SD}	I _S = - 5.6 A, V _{GS} = 0 V		- 0.71	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			22	33	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			17	26	nC	
Reverse Recovery Fall Time	t _a	$I_F = -5.6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		13			
Reverse Recovery Rise Time	t _b			9		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



T_C = - 55 °C

2.0

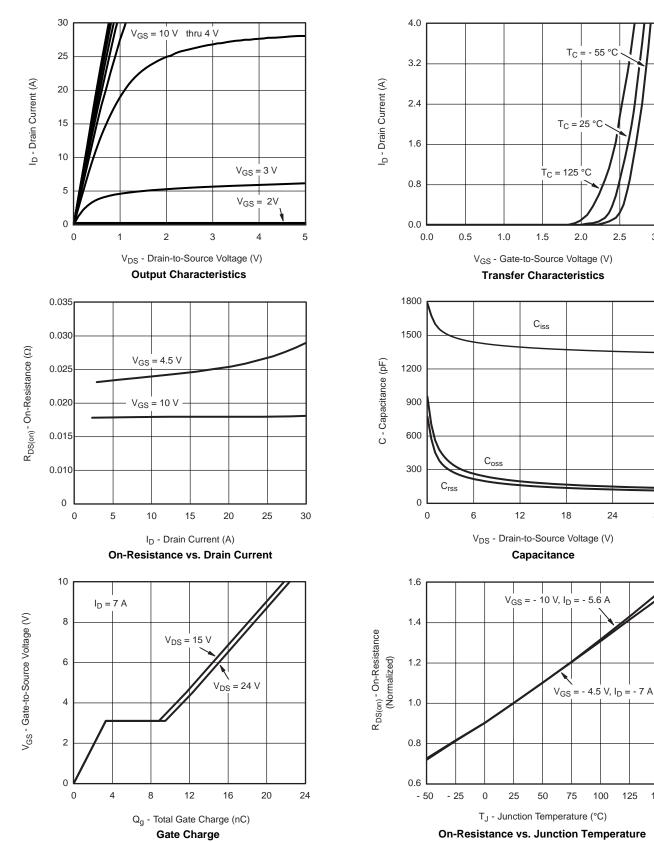
2.5

24

5.6 A

30

3.0



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

125

75

100

150

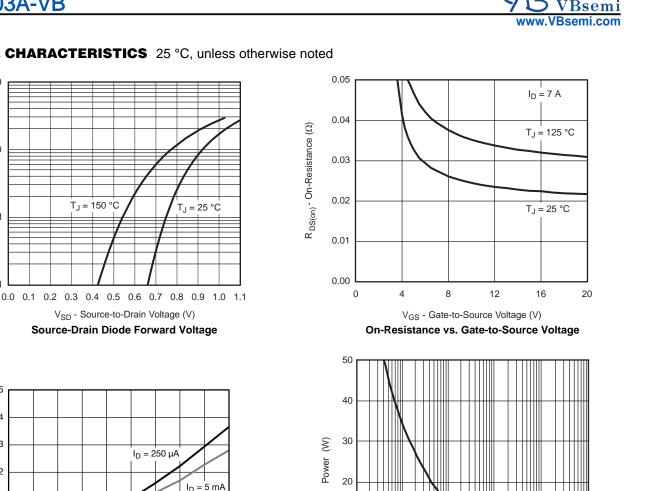
100

10

1

0.1

I_S - Source Current (A)



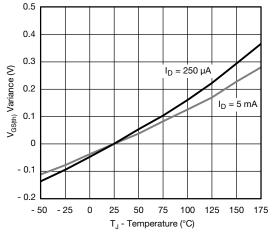
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

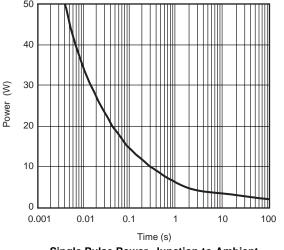
T_J = 25 °C

T_J = 150 °C

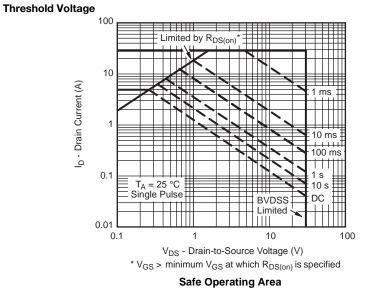
V_{SD} - Source-to-Drain Voltage (V)

Source-Drain Diode Forward Voltage



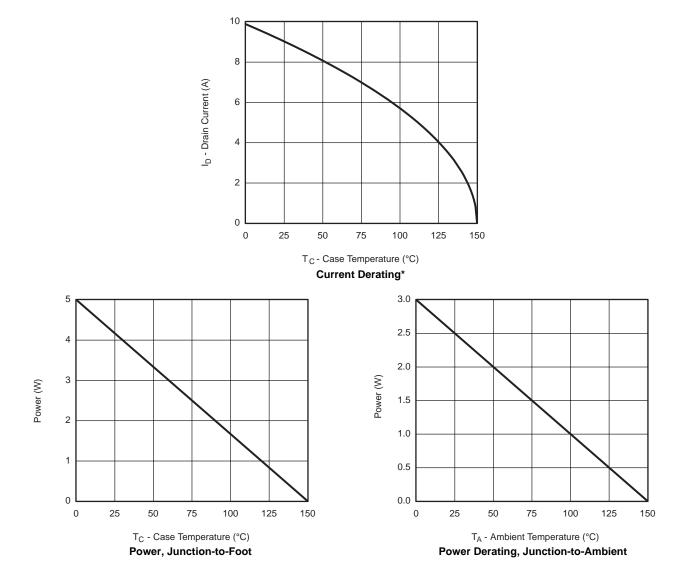








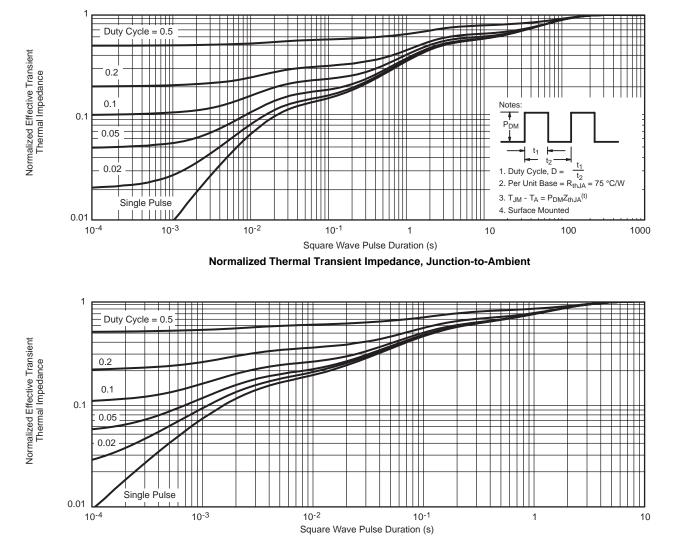
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



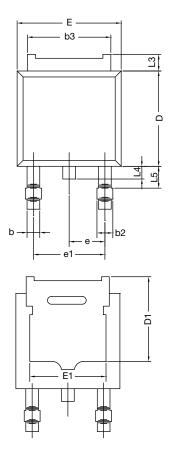
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot



TO-252AA CASE OUTLINE





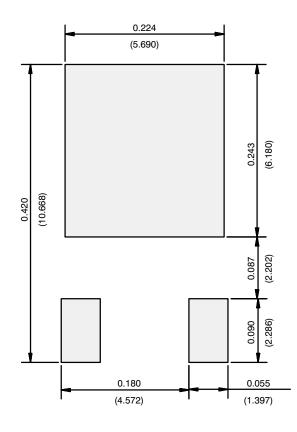
	MILLIMETERS		INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
А	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	5.21	-	0.205	-		
Е	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28	BSC	0.090 BSC			
e1	4.56	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060		
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347						

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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